



## News Release

For Immediate Release

### **CyberOptics Semiconductor Introduces WaferSense Auto Leveling System 2**

*Wireless sensor enables greater wafer processing uniformity and real-time feedback  
to improve throughput and yield*

**BEAVERTON, ORE., and SAN FRANCISCO -- July 17, 2007** -- CyberOptics Semiconductor, a subsidiary of CyberOptics Corp. (Nasdaq: CYBE), announces its WaferSense™ Auto Leveling System 2 (ALS2), a new generation of its wireless, wafer-like inclinometer in a 6.3 mm tall form factor. Compared with previous models, its thinner design allows the leveling wafer to automatically move to more stations within wafer processing equipment. Like all WaferSense products, the ALS2 enables quick and accurate measurements wirelessly for faster set-up and adjustment of semiconductor wafer processing and automation equipment, helping to keep equipment running longer while significantly reducing defects due to misaligned equipment.

As semiconductor device ASPs continue to decline, manufacturers must find ways to minimize downtime while maximizing yield. The ALS2 is designed specifically to help fab engineers improve wafer processing. Its wireless design and real-time feedback provide a significantly more reliable and accurate method for keeping equipment aligned to tight specifications than traditional wired or manual methods. Better alignment enables fabs to achieve higher levels of throughput, and greater tool-to-tool uniformity moves the industry closer to achieving the promise of 300 mm Prime.

“The semiconductor industry is in critical need of new tools that will enable fabs to operate more efficiently. Key to this goal is keeping equipment running smoothly, because misaligned wafer processing equipment can take a considerable toll on a semiconductor manufacturer’s bottom line,” said Craig Ramsey, general manager at CyberOptics Semiconductor. “WaferSense ALS2 helps engineers quickly check and adjust level and coplanarity so fab equipment gets back online faster. Improved yield and throughput are realized by reducing wafer scrap and contamination enabling the production of more good wafers.”

The WaferSense ALS2 sensor comes in 200 mm and 300 mm sizes and is designed to be handled like a wafer. It can be placed in cassettes, FOUPs, on end effectors, aligners, in load locks, transfer pins or process chamber pedestals to quickly ensure that all stations are level and

coplanar. The device has an inclination measurement range of  $\pm 14$  degrees from horizontal, and provides precise pitch and roll measurements – accurate to  $\pm 0.03$  degrees – that can be logged to relate coplanarity with yield and determine the ideal tool set-up for optimal yields. Vacuum compatible, the wireless device enables fab engineers to take measurements without breaking down the equipment or exposing process areas to the fab environment, saving both time and money in wasted consumables.

WaferSense tools offer real-time feedback of equipment measurements via Bluetooth connectivity. LevelView™, the graphical user interface software included with ALS2, displays an intuitive bubble level metaphor that shortens maintenance times. New slope and polar measurement units enhance ease of use. Using the leveling wafer and LevelView to collect and display inclination data wirelessly lets fab engineers see the effect of their adjustments in real time. Levels can be set to any reference plane within the sensor's operating range, and users can define Go/No Go regions, as well as log data and notes for future reference. As a result, alignment problems can be diagnosed and remedied quickly, equipment is returned to productive use faster, and fabs realize better tool-to-tool process uniformity and greater yield.

### **WaferSense Auto Leveling System 2 Key Specifications**

- Form factors: SEMI 200 mm notch or flat, and 300 mm notch form factors
- Accuracy:  $\pm 0.03$  degrees within  $\pm 7$  degrees from horizontal
- Resolution:  $\pm 0.002$  degrees within  $\pm 14$  degrees from horizontal
- Operating temperature: 20 to 70 degrees C
- Thin (6.3 mm tall) and light (200 mm, 150g; 300 mm, 240g)
- Bluetooth communications link
- Operates for four hours between recharging
- For use with Windows 2000, XP and Vista operating systems

WaferSense ALS2 package includes the leveling wafer, communications link, LevelView applications software, charging box and carrying case.

### **About CyberOptics Semiconductor:**

CyberOptics Semiconductor is a subsidiary of CyberOptics Corp. (Nasdaq: CYBE), one of the world's leading providers of process yield and throughput improvement solutions for electronic assembly and semiconductor capital equipment companies. For more information, visit the web site at: [www.CyberopticsSemi.com](http://www.CyberopticsSemi.com), e-mail [CSsales@cyberoptics.com](mailto:CSsales@cyberoptics.com), or call 800-366-9131.

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